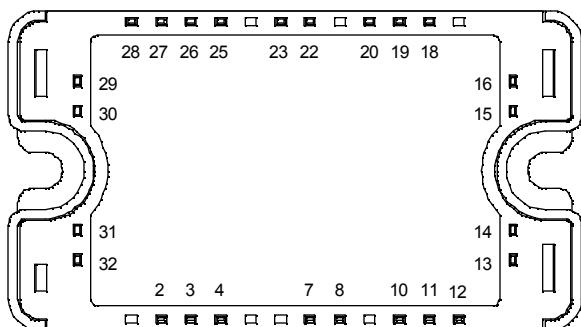
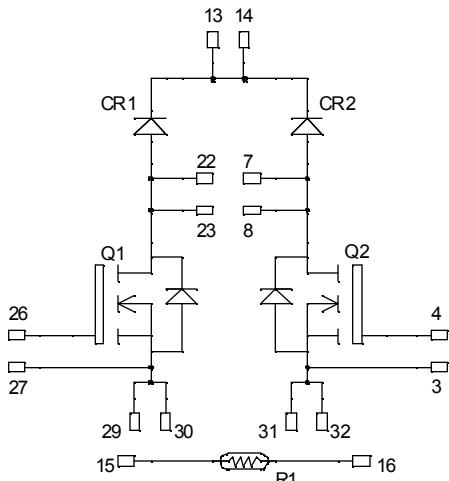


**Dual Boost chopper  
Super Junction MOSFET  
Power Module**

**V<sub>DSS</sub> = 800V**  
**R<sub>DSon</sub> = 150mΩ max @ T<sub>j</sub> = 25°C**  
**I<sub>D</sub> = 28A @ T<sub>c</sub> = 25°C**



All multiple inputs and outputs must be shorted together

Example: 13/14 ; 29/30 ; 22/23 ...

**Absolute maximum ratings**

Symbol	Parameter	Max ratings	Unit
V <sub>DSS</sub>	Drain - Source Breakdown Voltage	800	V
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> = 25°C T <sub>c</sub> = 80°C	28 21
I <sub>DM</sub>	Pulsed Drain current		
V <sub>GS</sub>	Gate - Source Voltage	±30	V
R <sub>DSon</sub>	Drain - Source ON Resistance	150	mΩ
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C	277
I <sub>AR</sub>	Avalanche current (repetitive and non repetitive)		A
E <sub>AR</sub>	Repetitive Avalanche Energy	0.5	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy	670	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

**Application**

- AC and DC motor control
- Switched Mode Power Supplies
- Power Factor Correction

**Features**



- Ultra low R<sub>DSon</sub>
- Low Miller capacitance
- Ultra low gate charge
- Avalanche energy rated
- Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
- Internal thermistor for temperature monitoring
- High level of integration

**Benefits**

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- Each leg can be easily paralleled to achieve a single boost of twice the current capability

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$\text{BV}_{\text{DSS}}$	Drain - Source Breakdown Voltage	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 375\text{\mu A}$	800			V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = 800\text{V}$	$T_j = 25^\circ\text{C}$		50	$\mu\text{A}$
		$\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = 800\text{V}$	$T_j = 125^\circ\text{C}$		375	
$\text{R}_{\text{DS(on)}}$	Drain – Source on Resistance	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 14\text{A}$			150	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}} = \text{V}_{\text{DS}}, \text{I}_D = 2\text{mA}$	2.1	3	3.9	V
$\text{I}_{\text{GSS}}$	Gate – Source Leakage Current	$\text{V}_{\text{GS}} = \pm 20\text{ V}, \text{V}_{\text{DS}} = 0\text{V}$			$\pm 150$	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$\text{C}_{\text{iss}}$	Input Capacitance	$\text{V}_{\text{GS}} = 0\text{V}$ $\text{V}_{\text{DS}} = 25\text{V}$ $f = 1\text{MHz}$		4507		pF
$\text{C}_{\text{oss}}$	Output Capacitance			2092		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance			108		
$\text{Q}_g$	Total gate Charge	$\text{V}_{\text{GS}} = 10\text{V}$ $\text{V}_{\text{Bus}} = 400\text{V}$ $\text{I}_D = 28\text{A}$		180		nC
$\text{Q}_{\text{gs}}$	Gate – Source Charge			22		
$\text{Q}_{\text{gd}}$	Gate – Drain Charge			90		
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	<b>Inductive switching @ 125°C</b> $\text{V}_{\text{GS}} = 15\text{V}$ $\text{V}_{\text{Bus}} = 533\text{V}$ $\text{I}_D = 28\text{A}$ $R_G = 2.5\Omega$		10		ns
$\text{T}_r$	Rise Time			13		
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time			83		
$\text{T}_f$	Fall Time			35		
$\text{E}_{\text{on}}$	Turn-on Switching Energy ①	<b>Inductive switching @ 25°C</b> $\text{V}_{\text{GS}} = 15\text{V}, \text{V}_{\text{Bus}} = 533\text{V}$ $\text{I}_D = 28\text{A}, R_G = 2.5\Omega$		486		$\mu\text{J}$
$\text{E}_{\text{off}}$	Turn-off Switching Energy ②			278		
$\text{E}_{\text{on}}$	Turn-on Switching Energy ①			850		
$\text{E}_{\text{off}}$	Turn-off Switching Energy ②	<b>Inductive switching @ 125°C</b> $\text{V}_{\text{GS}} = 15\text{V}, \text{V}_{\text{Bus}} = 533\text{V}$ $\text{I}_D = 28\text{A}, R_G = 2.5\Omega$		342		$\mu\text{J}$

**Diode ratings and characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$\text{V}_{\text{RRM}}$	Maximum Peak Repetitive Reverse Voltage		1000			V	
$\text{I}_{\text{RM}}$	Maximum Reverse Leakage Current	$\text{V}_R = 1000\text{V}$	$T_j = 25^\circ\text{C}$		250	$\mu\text{A}$	
			$T_j = 125^\circ\text{C}$		500		
$\text{I}_{\text{F(AV)}}$	Maximum Average Forward Current	50% duty cycle	$T_c = 100^\circ\text{C}$	60		A	
$\text{V}_F$	Diode Forward Voltage	$I_F = 60\text{A}$		1.9	2.5	V	
		$I_F = 120\text{A}$		2.2			
		$I_F = 60\text{A}$	$T_j = 125^\circ\text{C}$	1.7			
$t_{\text{rr}}$	Reverse Recovery Time	$I_F = 60\text{A}$ $\text{V}_R = 667\text{V}$ $\text{di}/\text{dt} = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$	280		ns	
			$T_j = 125^\circ\text{C}$	350			
$Q_{\text{rr}}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$	760		nC	
			$T_j = 125^\circ\text{C}$	3600			

①  $E_{\text{on}}$  includes diode reverse recovery.

② In accordance with JEDEC standard JESD24-1.

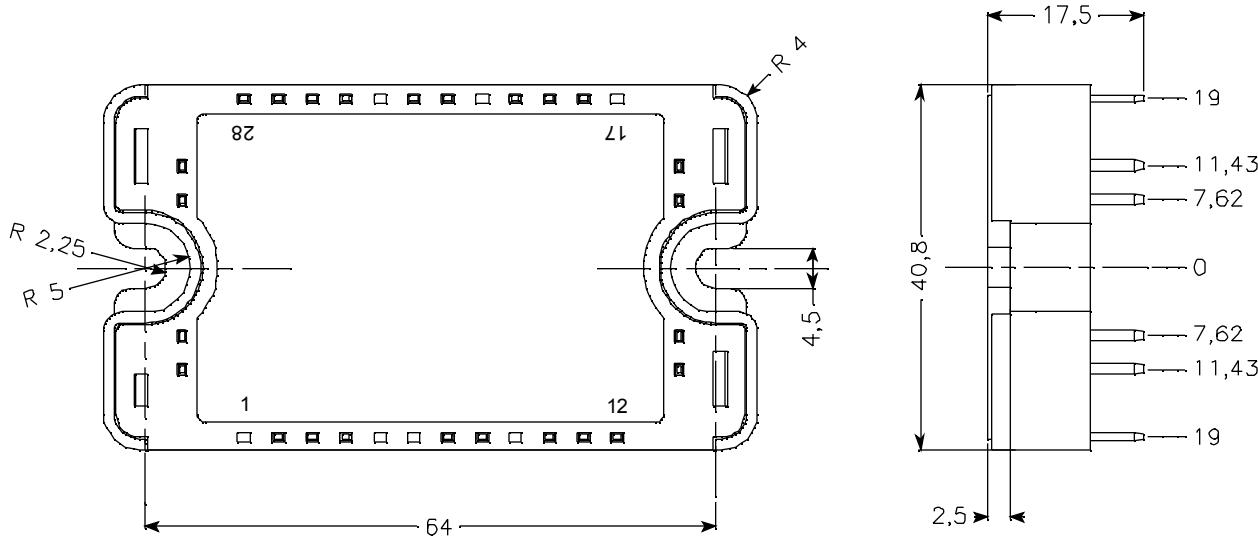
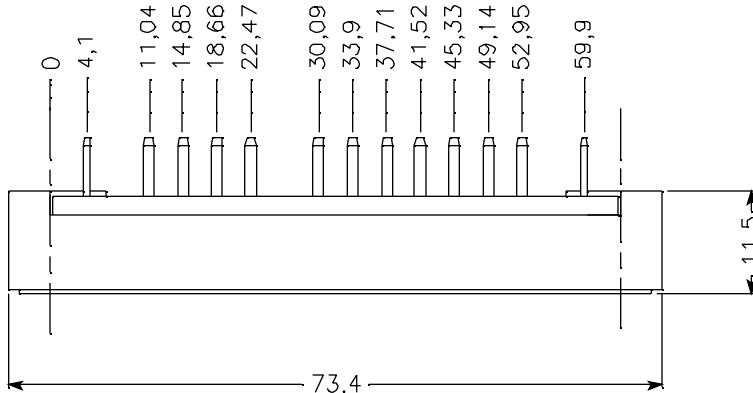
**Thermal and package characteristics**

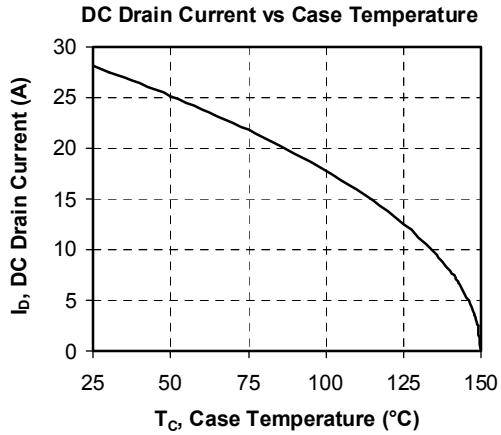
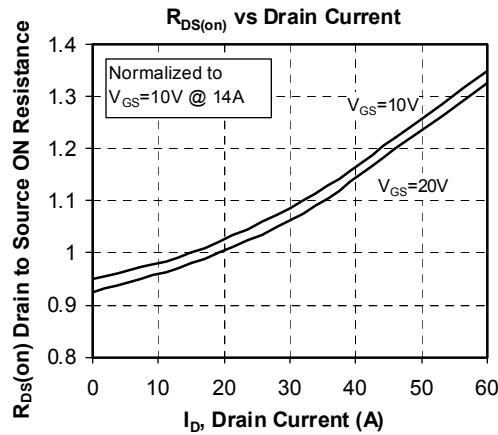
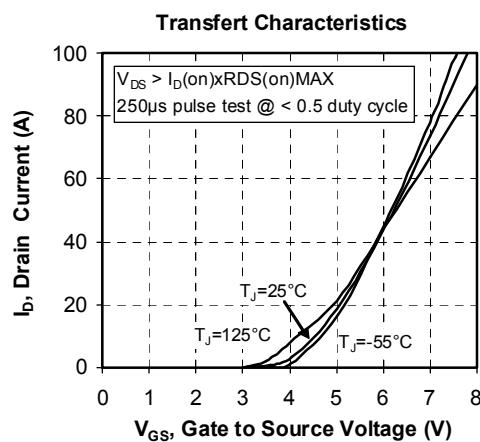
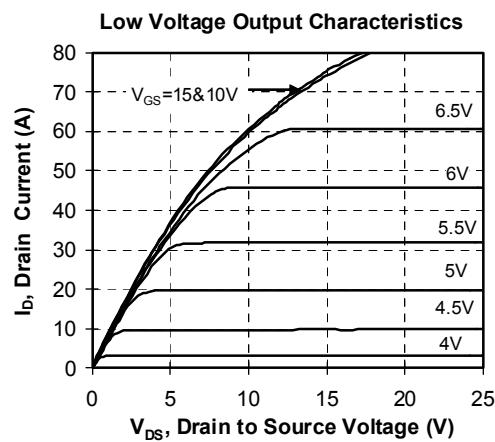
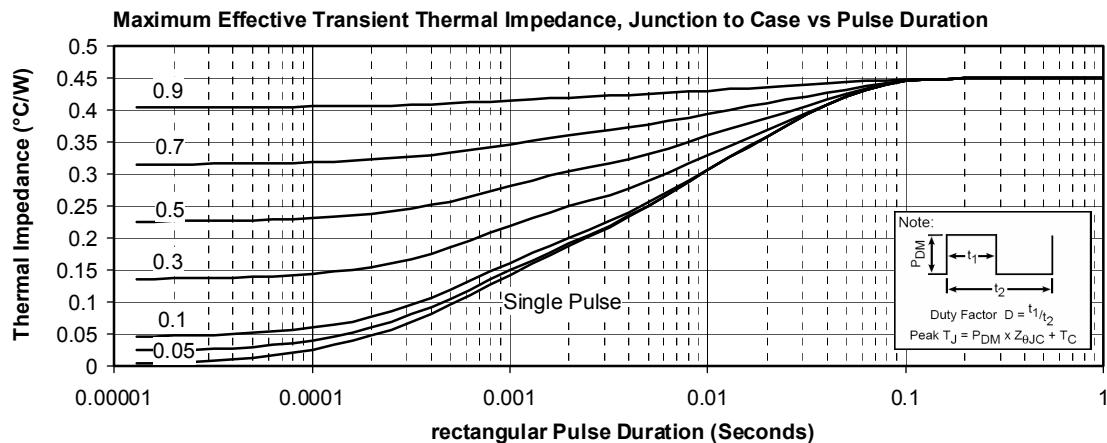
<i>Symbol</i>	<i>Characteristic</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R <sub>thJC</sub>	Junction to Case	IGBT			0.45	°C/W
		Diode			0.9	
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz		2500			V
T <sub>J</sub>	Operating junction temperature range		-40		150	
T <sub>STG</sub>	Storage Temperature Range		-40		125	°C
T <sub>C</sub>	Operating Case Temperature		-40		100	
Torque	Mounting torque	To heatsink	M4		4.7	N.m
Wt	Package Weight				110	g

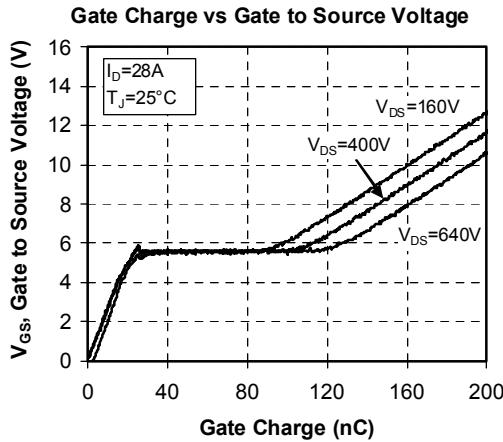
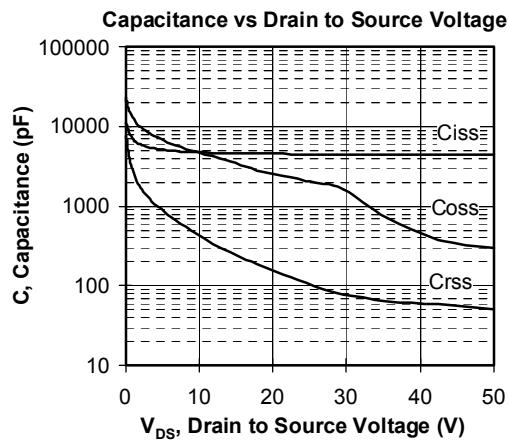
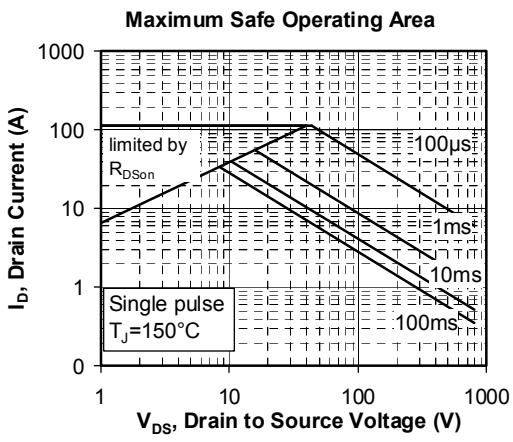
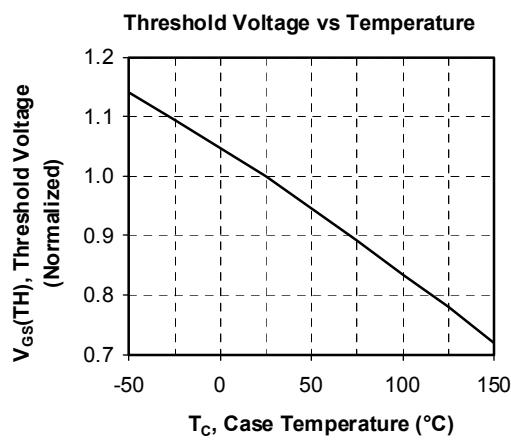
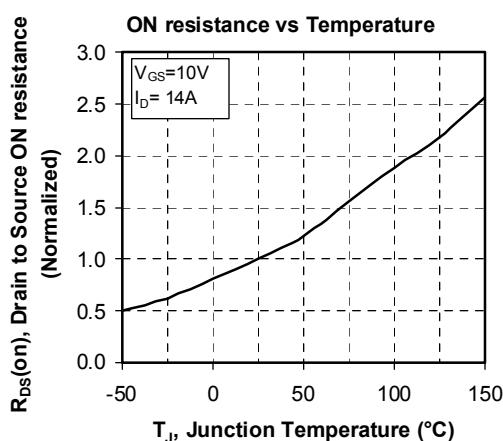
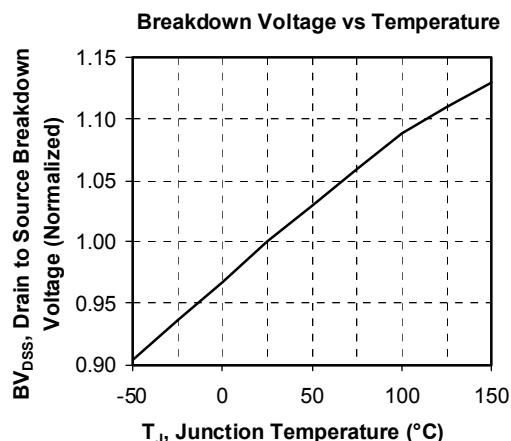
**Temperature sensor NTC**

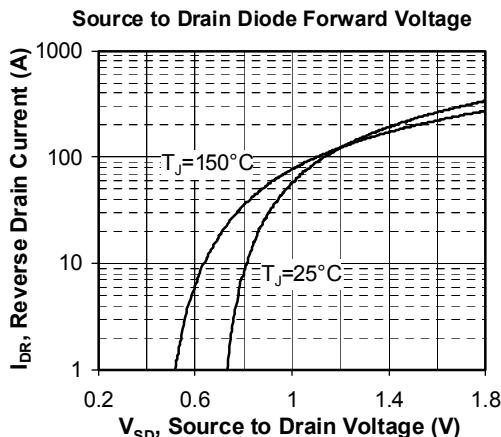
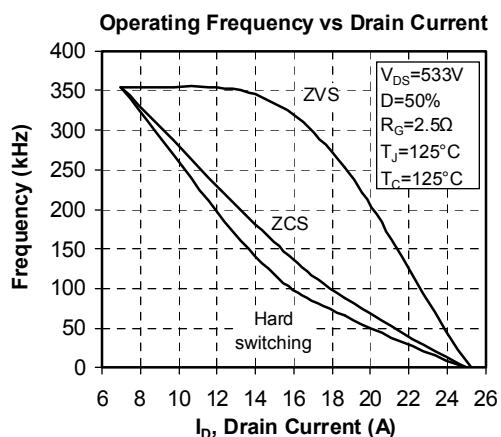
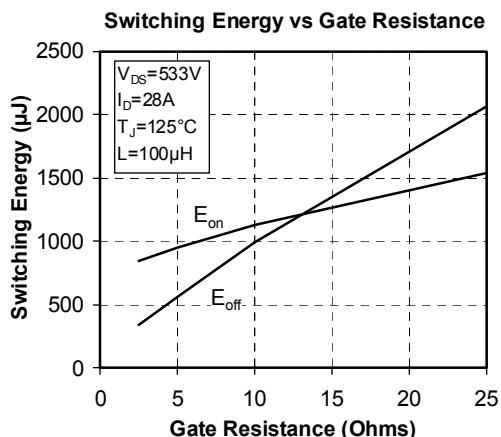
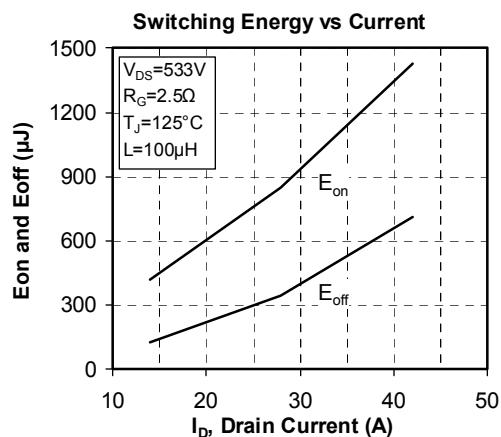
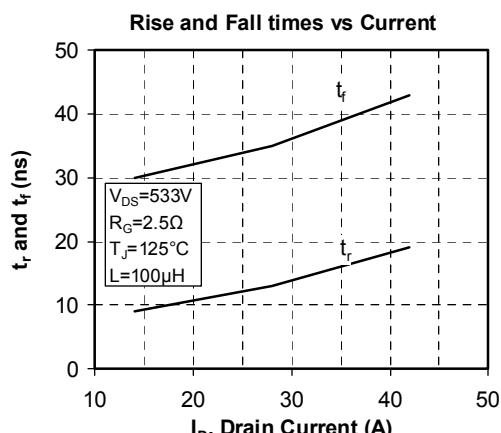
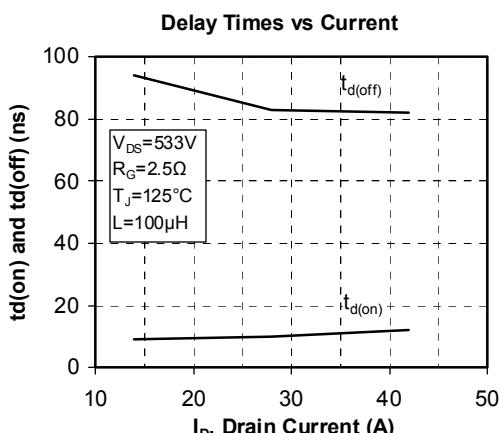
<i>Symbol</i>	<i>Characteristic</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R <sub>25</sub>	Resistance @ 25°C			68		kΩ
B <sub>25/85</sub>	T <sub>25</sub> = 298.16 K			4080		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]} \quad \begin{matrix} T: \text{Thermistor temperature} \\ R_T: \text{Thermistor value at } T \end{matrix}$$

**Package outline**


**Typical Performance Curve**






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